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(54) ELECTRONIC MODULE AND CONTACT ARRANGEMENT

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(57) ABSTRACT

An electronic module. The electronic module includes a circuit carrier having an electrical and/or electronic circuit. This circuit is completely embedded in an encapsulation molding compound. The electronic module includes an electrically contactable outer contact connection arranged on the enclosure, which has a press-fit zone. The contact connection is electrically connected to the electrical and/or electronic circuit on an upper side of the circuit carrier facing the press-fit zone. In the region of the press-in zone, the contact connection in the enclosure is free of the encapsulating compound. The contact connection is accommodated in a cavity of a holding frame made of a plastics material. The cavity is formed by a closed wall running around the contact connection, which rests on the upper side of the circuit carrier and projects in a direction of the press-fit zone. The wall separates the cavity from the encapsulating compound.

